

# **Non-Linear High Speed Termination IC**

#### **Features**

- 16 channel, dual rail clamping action in a single package
- Provides bus termination independent of line impedance or loading conditions
- Uses CAMD's patented EZterm<sup>™</sup> technology
- 24-pin QSOP package saves board space and eases layout in space critical areas.
- One IC replaces and outperforms up to 32 discrete components.
- Enable pin included

### **Product Description**

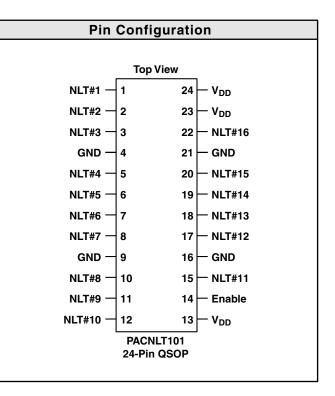
CAMD's non-linear termination IC is specifically designed to minimize overshoot/undershoot disturbances caused by impedance mismatch reflections and noise on high-speed transmission lines.

Reflections on high-speed data lines lead to voltage overshoot and undershoot disturbances, which may result in data loss or improper system operation. Resistive terminations, when used to terminate these highspeed data lines, increase power consumption and degrade output levels, resulting in reduced noise immunity. Clamping-type termination is the best overall solution for applications in which these may be considerations.

This highly integrated non-linear termination IC provides very effective termination performance for high-speed data lines under variable loading conditions. The device supports up to 16 terminated lines per package – each of which are clamped to both ground and power supply rail. A typical application may use 4 devices to replace (and outperform) 64 conventional Schottky diode pairs; thus providing significant reductions in component and assembly costs, improvements in manufacturing efficiency and reliability, and savings in allocated board area for space-critical designs.

## Application

· High speed, low voltage buses



Standard Part Ordering Information					
Package Ordering Part Number			art Number		
Pin	Style	Tape & Reel	Part Marking		
24	QSOP	PACNLT101Q	PACNLT101Q		

Absolute Maximum Ratings					
Parameter	Rating	Unit			
Maximum DC Voltage on any pin	3.6	V			
Minimum DC Voltage on any pin	-0.5	V			
Continuous current per channel	72	mA			
Operating Temperature (Ambient)	-40 to 85	°C			
Storage Temperature (Ambient)	-65 to 150	°C			
Power Dissipation @ T = 25°C	0.9	W			

## **Operating Characteristics -** $V_{DD}$ = 3.3V, Enable = 3.3V, Temperature = -40°C to 85°C

Operating Characteristics — 3.3V					
Parameter	Conditions	MIN	TYP	MAX	UNIT
Signal Voltage	above $V_{DD}$ @ I = 50mA		610	850	mV
	below GND @ I = -50mA		510	750	mV
V <sub>DD</sub> current	all Channels floating		85	150	mA
Enable pin (pin 14) current	all Channels floating		10	15	mA
Input Capacitance*	Signal voltage = V <sub>DD</sub>		3.4		pF
	Signal voltage = V <sub>DD/2</sub>		3.0		pF
ESD protection	MIL-STD-883, method 3015*	4			kV
Response Time				400	ps

\*These parameters are guaranteed by design and characterization.

## **Operating Characteristics -** $V_{DD}$ = 2V, Enable = 2V, Temperature = -40°C to 85°C

Operating Characteristics — 2.0V					
Parameter	Conditions	MIN	ТҮР	МАХ	UNIT
Signal Voltage	above V <sub>DD</sub> @ I = 20mA		390	600	mV
	below GND @ I = -20mA		300	500	mV
V <sub>DD</sub> current	all Channels floating		25	42	mA
Enable pin (pin 14) current	all Channels floating		3.5	5.5	mA
Input Capacitance*	Signal voltage = V <sub>DD</sub>		3.5		pF
	Signal voltage = V <sub>DD/2</sub>		3.2		рF
ESD protection	MIL-STD-883, method 3015*	4			kV
Response Time				400	ps

\*These parameters are guaranteed by design and characterization.

## **Operating Characteristics -** $V_{DD}$ = 2.5V, Enable = 2.5V, Temperature = 27°C

Operating Characteristics — 2.5V					
Parameter	Conditions	MIN	ТҮР	MAX	UNIT
Signal Voltage	above V <sub>DD</sub> @ I = 30mA		470		mV
	below GND @ I = -30mA		375		mV
V <sub>DD</sub> current	all Channels floating		50		mA
Enable pin current	all Channels floating		6		mA

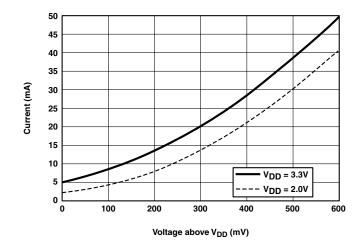


Figure 1. DC I-V Curves for  $V_{DD} = 2V$  and  $V_{DD} = 3.3V$ 

### **Application Information**

Figure 2 shows one method of configuring the printed circuit board such that all 16 terminated signals are easily accessible. The decoupling capacitor should be a high-frequency type,  $0.1\mu$ F or larger, and placed as close to the IC as possible. This will minimize

the positive overshoot voltage and also reduce EMI emissions. It should be noted that for optimum performance the PACNLT101 termination should be located as physically close to the receiving IC input as is possible.

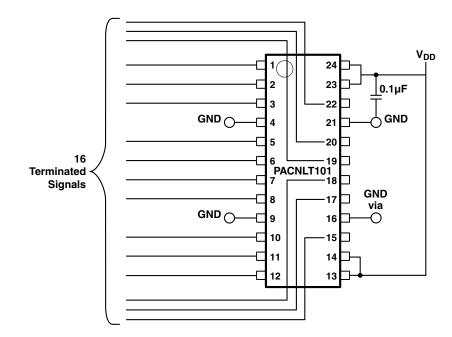


Figure 2. Printed Circuit Board with Accessible Configuration for 16 Terminated Signals

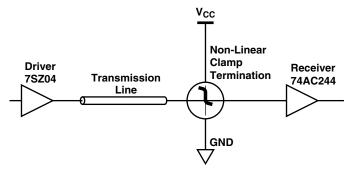
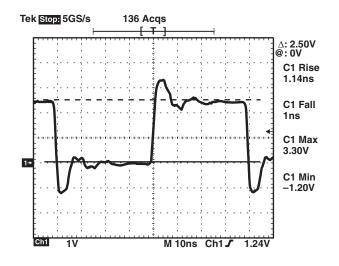
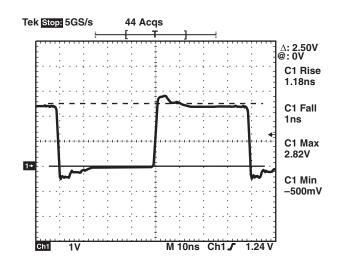


Figure 3. Example Circuit: Single-Driver/Single Receiver









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### Enable pin

In normal use the Enable pin is connected to  $V_{DD}$ .

If the Enable pin is set to 0V or disconnected (high impedance), then the PACNLT101 will be disabled. The supply current will drop to almost zero and the clamping performance will be worsened.

The Enable pin can also be used to vary the supply current and clamping voltage. As the current into the Enable pin is increased the supply current will increase and the clamping voltage will be reduced. The minimum clamping voltage will occur when the Enable pin voltage equals the supply voltage. (The Enable pin voltage cannot exceed the supply voltage.)

Users who cannot tolerate the supply current quoted in the Operating Characteristics can connect a resistor in series with the Enable pin to reduce the supply current, at the cost of increasing the clamping voltage. See Figure 6.

The controller IC sets the powerdown pin to 0V to powerdown the PACNLT101, and sets the powerdown pin to  $V_{DD}$  to power up the PACNLT101. The system designer can vary the value of R1 to optimize the tradeoff between power consumption and clamping voltage. See Figure 7, 8, 9, and 10.

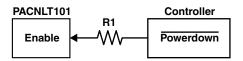


Figure 6. Resistor In Series with the Enable Pin

